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(12) **United States Design Patent** (10) **Patent No.:** **US D915,313 S**
Alfredsson et al. (45) **Date of Patent:** **** Apr. 6, 2021**

(54) **ELECTRONIC DEVICE HOUSING**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/184**; D13/110; D13/123

(58) **Field of Classification Search**
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D14/301, 439
CPC G05B 9/02; G05B 19/05; G05B 19/054;
G05B 19/056; G06F 1/182; G06F 1/183;
G06F 1/26; H05K 7/1462; H05K 7/1467;
H05K 7/1474; H05K 7/1432; H02B 1/26;
H02B 1/30; H02B 1/305
See application file for complete search history.

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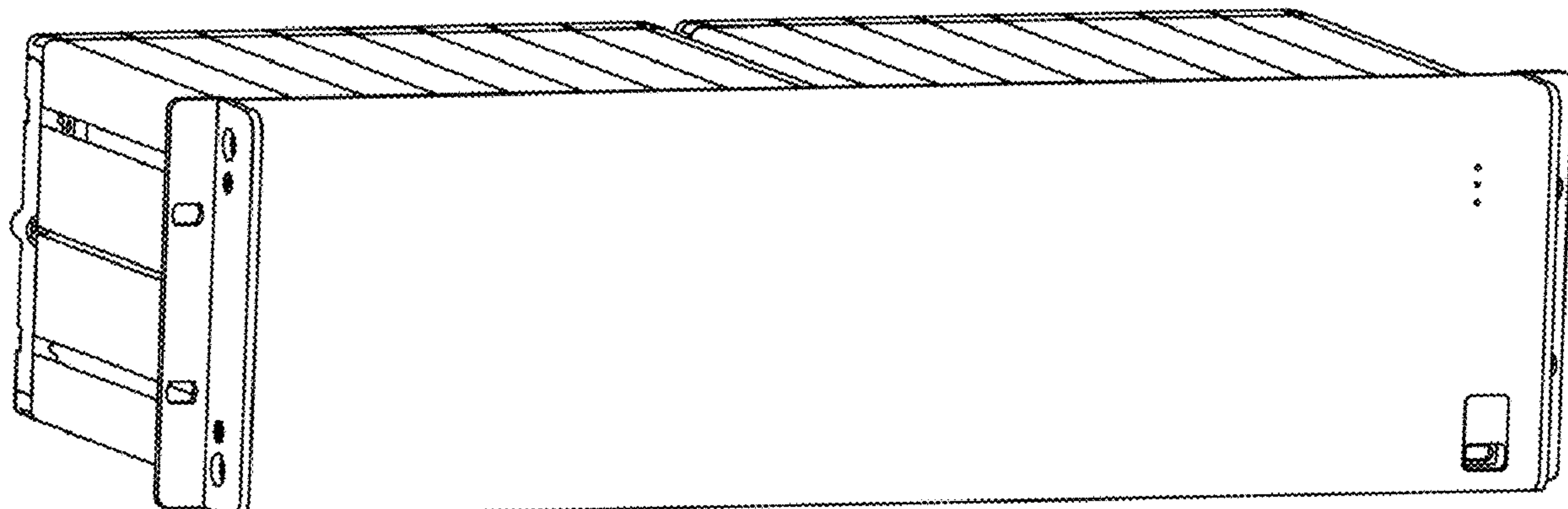
(57) **CLAIM**

The ornamental design for a electronic device housing, as shown and described.

DESCRIPTION

FIG. 1 is a top, front isometric view of electronic device housing in accordance with-the new design;
FIG. 2 is a right side elevational view of FIG. 1;
FIG. 3 is a left side elevational view of FIG. 1;
FIG. 4 is a front elevational view of FIG. 1;
FIG. 5 is a rear elevational view of FIG. 1;
FIG. 6 is a top plan view of FIG. 1; and,
FIG. 7 is a bottom plan view of FIG. 1.

1 Claim, 7 Drawing Sheets



(56)

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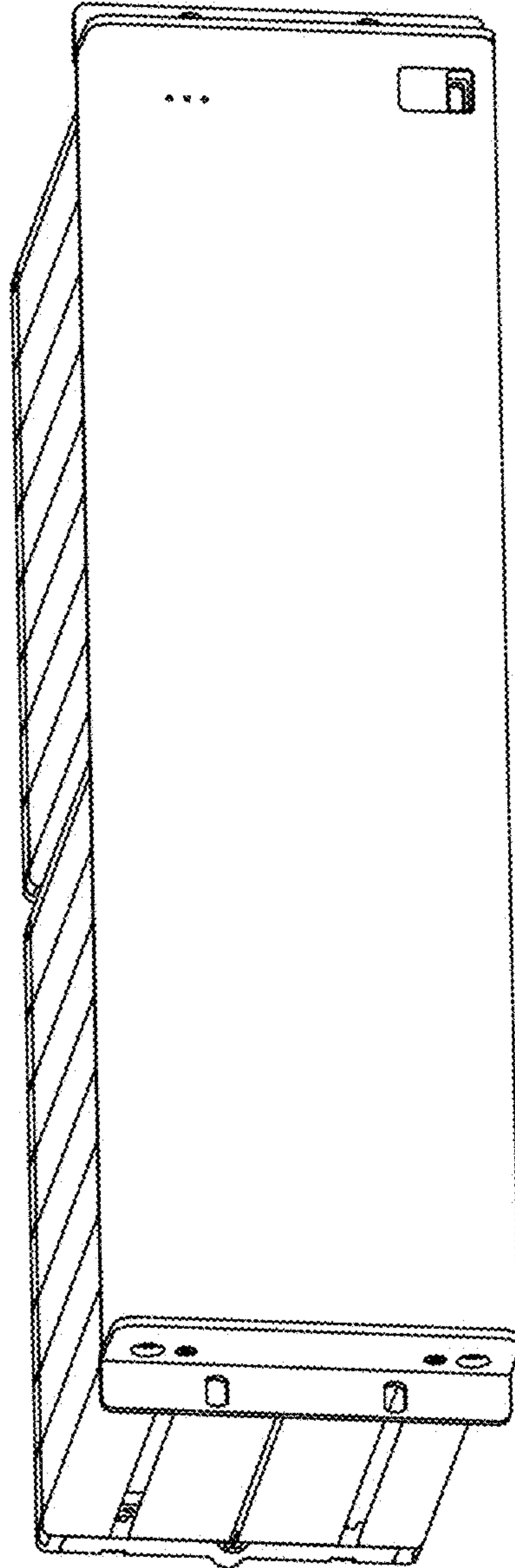


FIG. 1

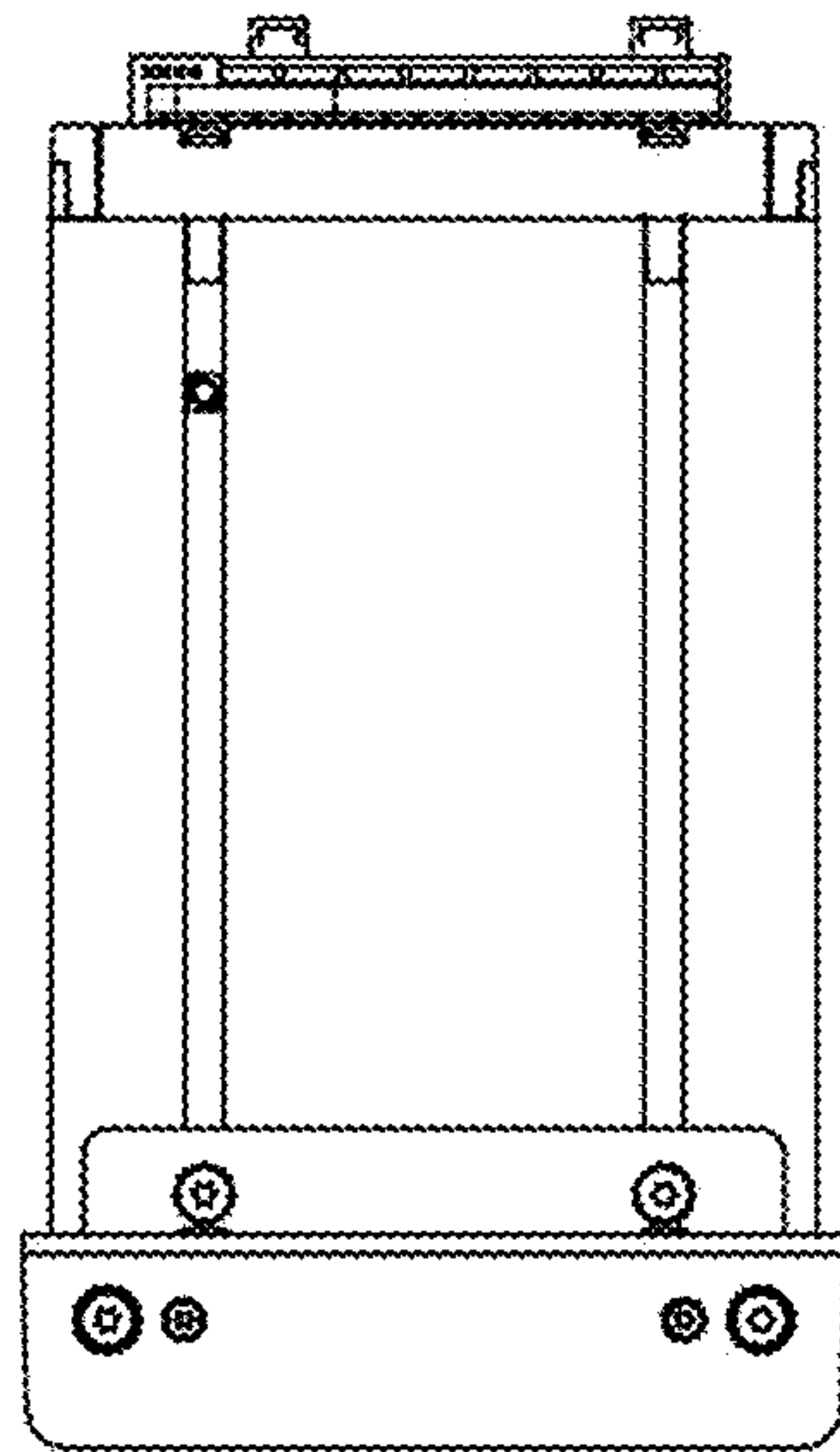


FIG. 2

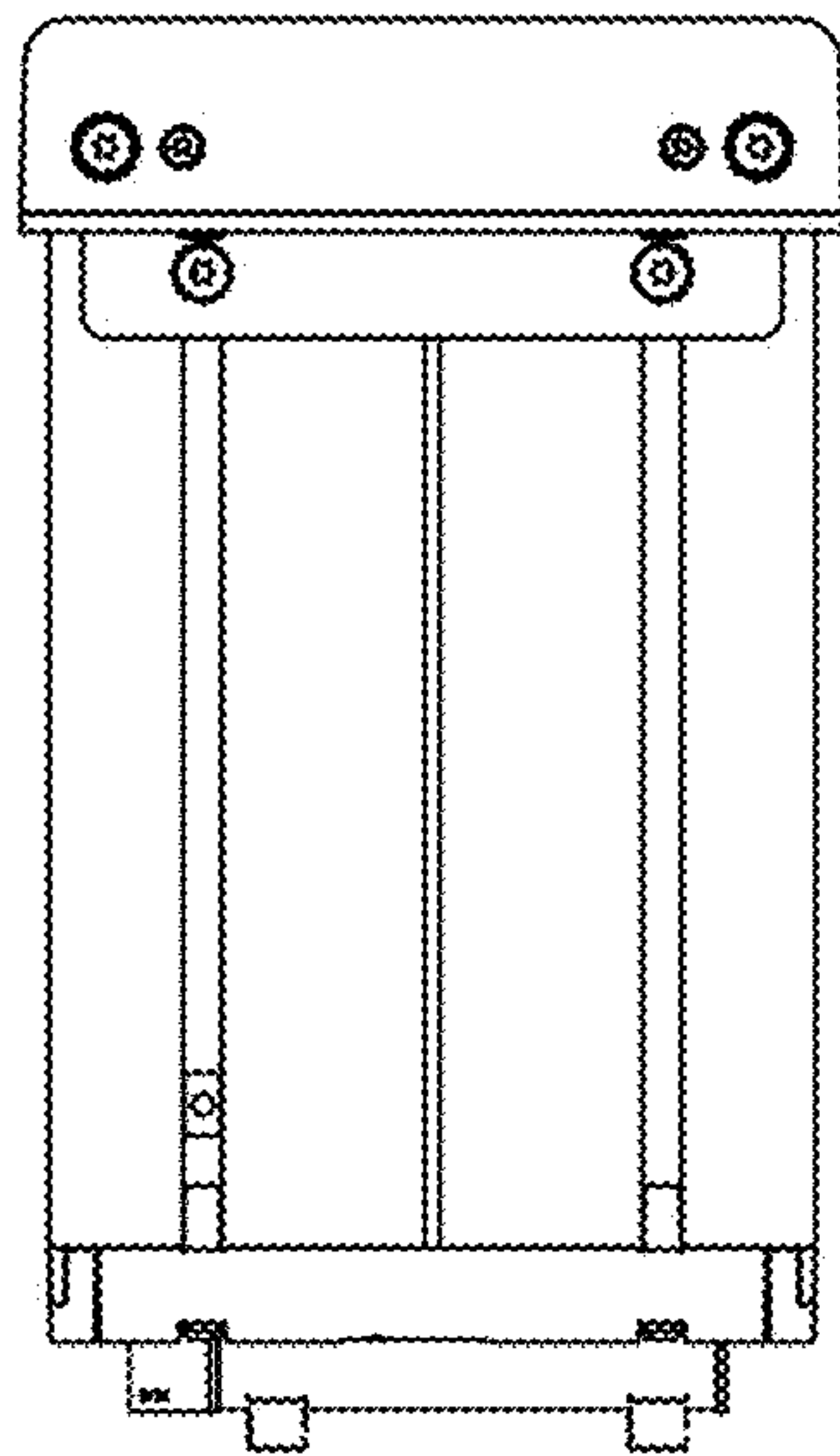


FIG. 3

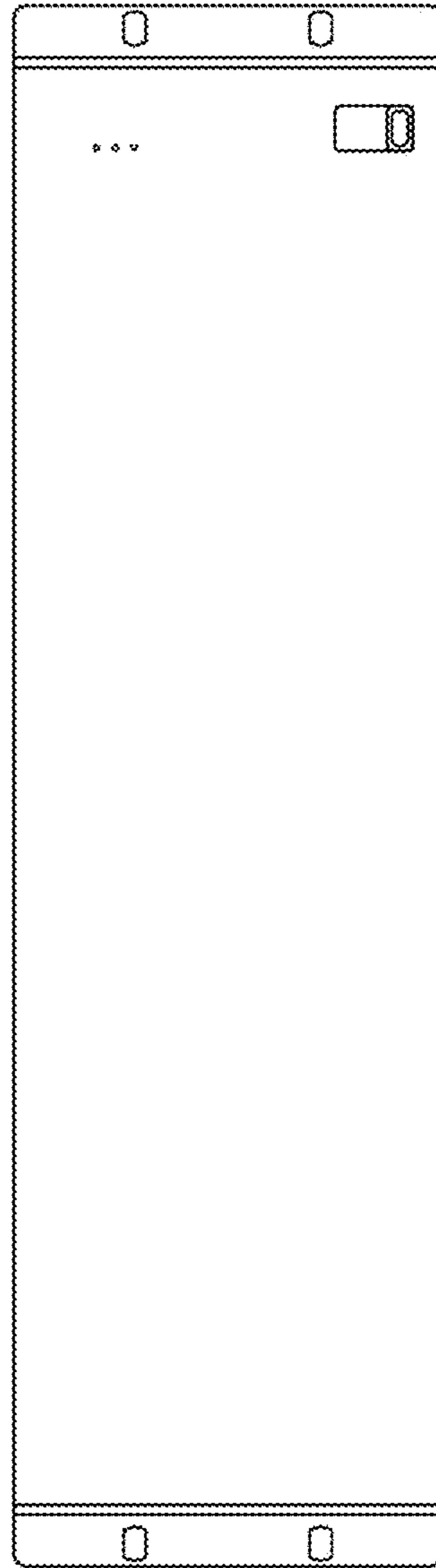


FIG. 4

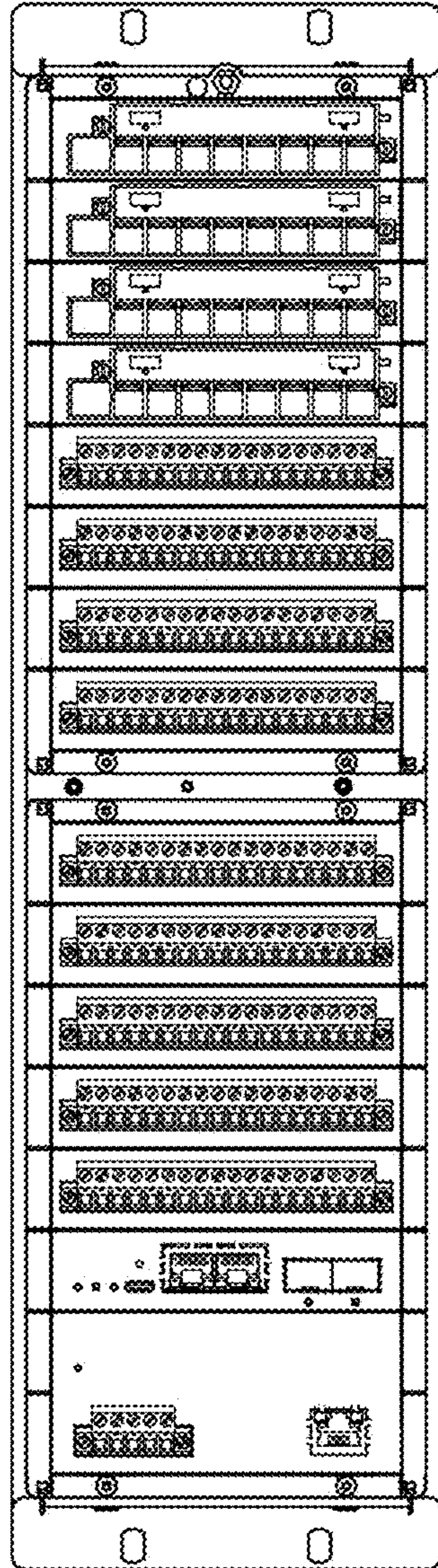


FIG. 5

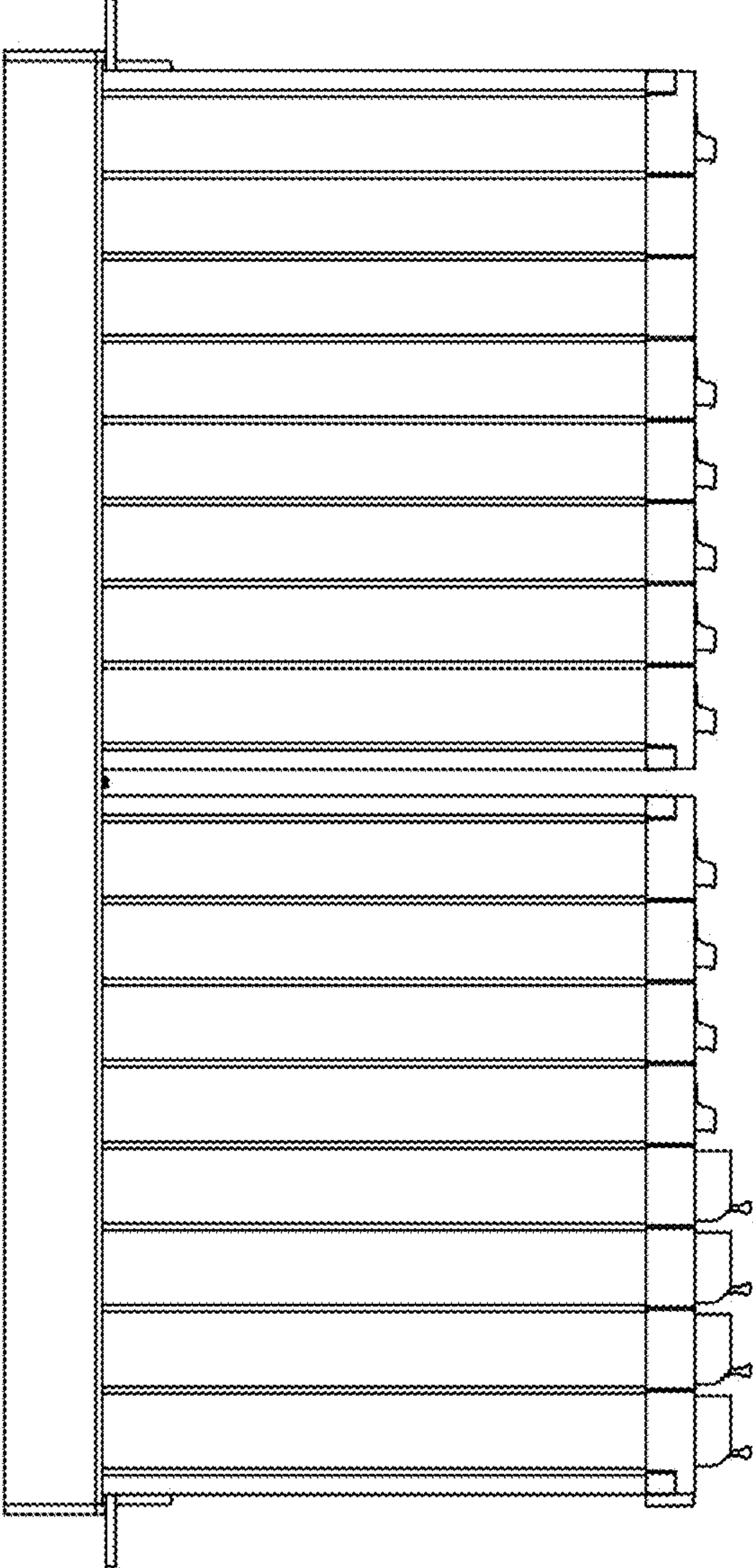


FIG. 6

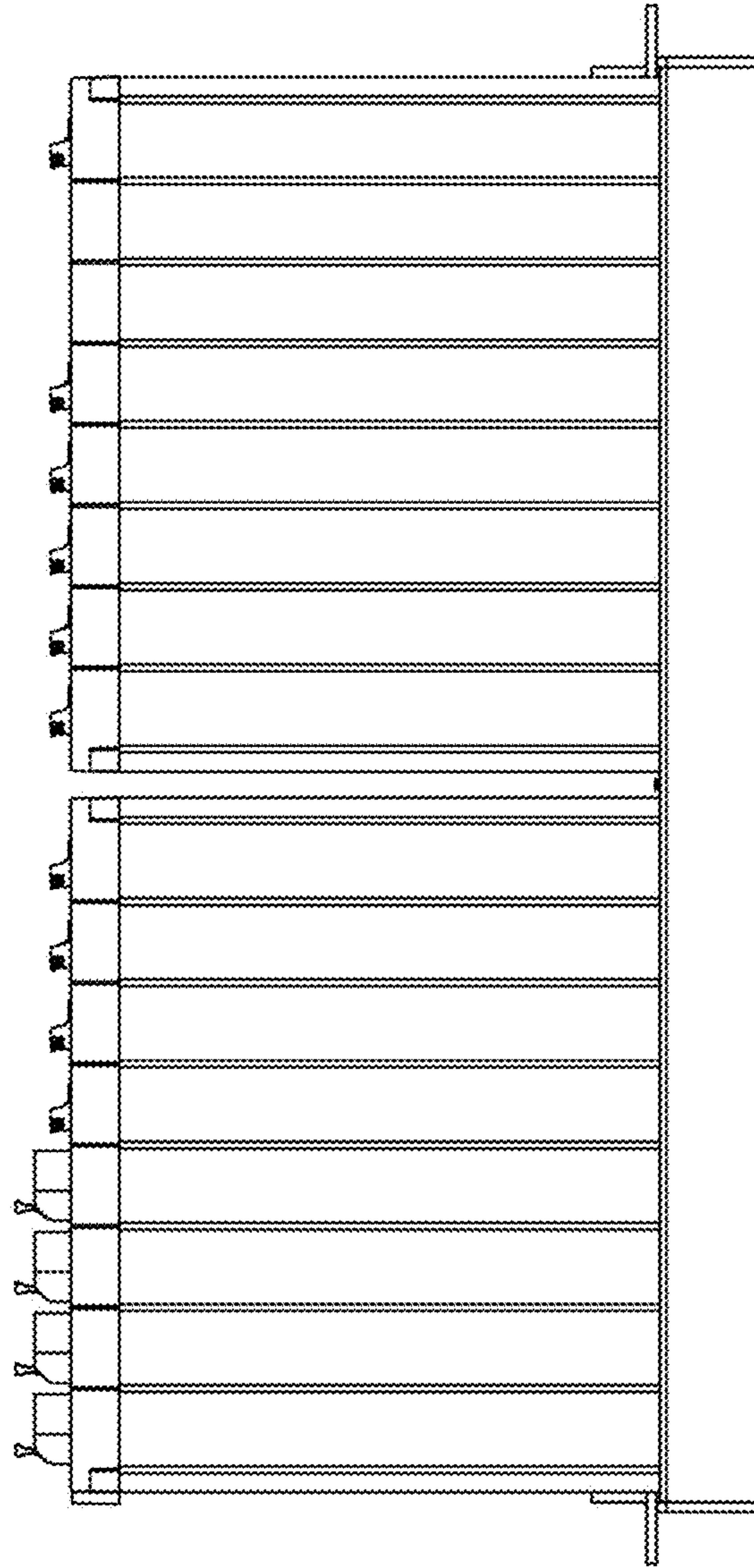


FIG. 7